

Specification Sheet

Cu, Purity: >99.9%, Thickness: 4mm

Stock No: NS6130-10-1010, CAS: 7440-50-8

Product	:	Pure Copper Foam
Stock No	:	NS6130-10-1010
CAS	:	7440-50-8
Purity	:	>99.9%
Porosity	:	>70%
Dimension	:	500mm X 500mm
Thickness	:	4mm
PPI	:	50
Molecular Formula	:	Cu
Molecular weight	:	63.55g/mol
Density	:	8.96g/cm ³
Melting point	:	1085°C
Boiling point	:	2562°C
Thermal expansion	:	16.5µm.m-1.k-1
Thermal conductivity	:	401W.m-1.k-1
Tensile strength	:	1.25N/mm
Young's modulus	:	110-128GPa
Shear strength	:	190Psi
Vickers hardness	:	369MPa
Poisson's ratio	:	0.34
Electrical resistivity	:	1.673µΩ-cm
Specific heat	:	0.39kj/kgK
Electronegativity	:	1.90paulings
Heat of fusion	:	13.26kJ.mol-1
Heat of vaporization	:	300.4kJ.mol-1

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Main Inspect Verifier

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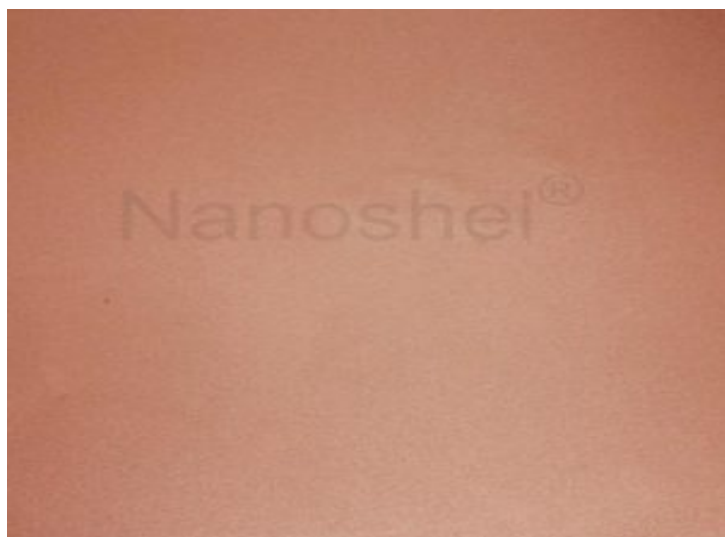
Manager QC



Note: Product Specification are subject to amendment and may change over time



Characterization of Cu, Purity: >99.9%, Thickness: 4mm



Pure Copper Foam



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